



TECHNICAL DATA

U_{max}	1.0 V	$T_{hot}=25^{\circ}C$ Dry air
Q_{max}	0.55 W	
ΔT_{max}	68°	
I_{max}	8.0 A	
ACR at 25°C	1.02 Ohm	
Lead wires type	Without lead wires	
Solder	Lead Free, m.p.t.≥227 °C	
Metallization	Cu+Ni+Au	
Hot side	Ceramics AlN, grey 99%	
Cold side		
Maximum processing temperature 180 °C		
Tolerances for thermal and electrical parameters ±10%		
This product is compliant to RoHS (2002/95/EC)		

AVAILABLE MODIFICATIONS

Design	Description
TM-9-0.3-0.9 TT	Standard design with metallization on both sides

MODIFICATIONS UPON REQUEST

Design	Description
TM-9-0.3-0.9	Standard design without metallization
TM-9-0.3-0.9 T	Standard design with metallization on hot side

STANDARD ORDERING OPTIONS

Nº	Option	Parameter
1	Lead wires availability	Only for samples
2	Lead wires type	Cu wire Sn plated $\phi 0.2$ mm, without insulation, L>30 mm, max. pr. temp. 200°C

For another options consult of our technical support engineers

Notes

- When applying plus voltage to positive lead wire the module cold side becomes heat absorbing surface.
- Module AC resistance at 25°C does not include resistance of lead wires.

Performance graphs for TM-9-0.28-0.9 modules at Th=25 °C
 Environment: dry air

